

<Intelligent Power Modules>

# PM300RG1C065

FLAT-BASE TYPE INSULATED PACKAGE



#### **FEATURE**

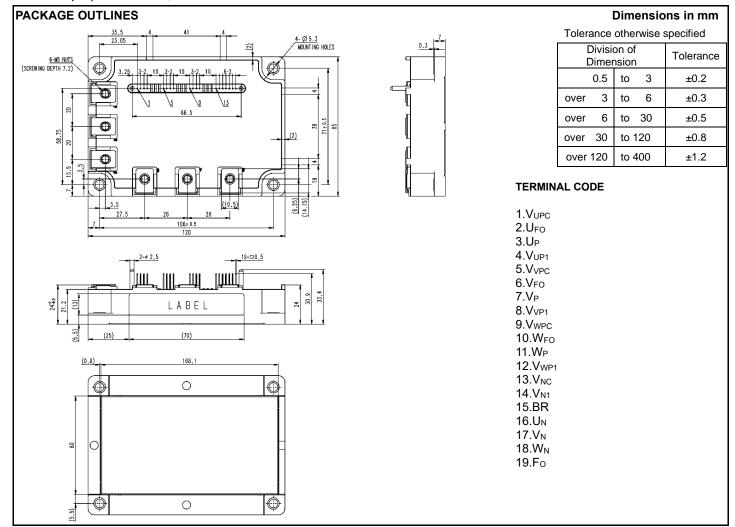
- a) Adopting Full-Gate CSTBT™ chip.
- b) The over-temperature protection which detects the chip surface temperature of CSTBT™ is adopted.
- c) Error output signal is available from each protection upper and lower arm of IPM.
- d) Outputting an error signal corresponding to the abnormal state (error mode identification)

UL Recognized under UL1557, File No. E323585
This product is compliant with the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive 2011/65/EU and (EU)2015/863.

#### **APPLICATION**

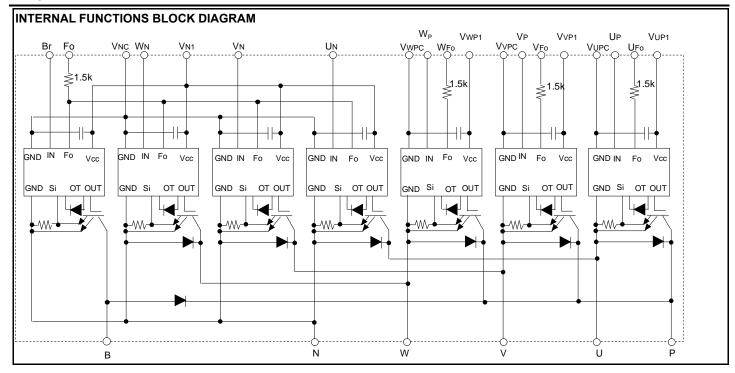
Publication date: December, 2020

General purpose inverter, servo drives and other motor controls



HIGH POWER SWITCHING USE

**INSULATED TYPE** 



#### **MAXIMUM RATINGS** (Tvj = 25°C, unless otherwise noted)

#### **INVERTER PART**

III EN I ANI							
Symbol	Parameter	Conditions	Ratings	Unit			
V <sub>CES</sub>	Collector-Emitter Voltage	V <sub>D</sub> =15 V, V <sub>CIN</sub> =15 V	650	V			
Ic	Collector Current	T <sub>C</sub> =25 °C	300	^			
I <sub>CRM</sub>	-Collector Current	Pulse	600	A			
P <sub>tot</sub>	Total Power Dissipation	T <sub>C</sub> =25 °C	1041	W			
I <sub>E</sub>	Emitter Current	T <sub>C</sub> =25 °C	300	_			
I <sub>ERM</sub>	(Free-wheeling Diode Forward current)	Pulse	600	A			
Tvj	Junction Temperature	(Note5)	-20 ~ +150	°C			

<sup>\*:</sup> Tc measurement point is just under the chip.

#### **BRAKE PART**

Symbol	Parameter	Conditions	Ratings	Unit
V <sub>CES</sub>	Collector-Emitter Voltage	V <sub>D</sub> =15 V, V <sub>CIN</sub> =15 V	650	V
I <sub>C</sub>	Callantan Comment	T <sub>C</sub> =25 °C	150	^
I <sub>CRM</sub>	Collector Current	Pulse	300	A
P <sub>tot</sub>	Total Power Dissipation	T <sub>C</sub> =25 °C	595	W
V <sub>R(DC)</sub>	Diode Rated Reverse DC Voltage	T <sub>C</sub> =25 °C	650	V
I <sub>F</sub>	Diode Forward Current	T <sub>C</sub> =25 °C	150	Α
Tvj	Junction Temperature	(Note5)	-20 ~ +150	°C

<sup>\*:</sup> To measurement point is just under the chip.

#### **CONTROL PART**

Symbol	Parameter	Conditions	Ratings	Unit
$V_D$	Supply Voltage	Applied between: V <sub>UP1</sub> -V <sub>UPC</sub> , V <sub>VP1</sub> -V <sub>VPC</sub> , V <sub>WP1</sub> -V <sub>WPC</sub> , V <sub>N1</sub> -V <sub>NC</sub>	20	V
$V_{CIN}$	Input Voltage	Applied between: $U_P$ - $V_{UPC}$ , $V_P$ - $V_{VPC}$ , $W_P$ - $V_{WPC}$ , $U_N$ , $V_N$ , $W_N$ , $W_N$ , $W_N$	20	V
$V_{FO}$	Fault Output Supply Voltage	Applied between: U <sub>FO</sub> -V <sub>UPC</sub> , V <sub>FO</sub> -V <sub>VPC</sub> , W <sub>FO</sub> -V <sub>WPC</sub> , Fo-V <sub>NC</sub>	20	V
I <sub>FO</sub>	Fault Output Current	Sink current at U <sub>FO</sub> , V <sub>FO</sub> , W <sub>FO</sub> , Fo terminals	20	mA

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#### **TOTAL SYSTEM**

Symbol	Parameter	Conditions	Ratings	Unit
V <sub>CC(PROT)</sub>	Supply Voltage Protected by SC	V <sub>D</sub> =13.5 V~16.5 V, Inverter Part, Tvj=+125°C start	400	V
T <sub>stg</sub>	Storage Temperature	-	-40 ~ +125	°C
Tc	Operating Case Temperature	(Note5)	-20 ~ +125	°C
V <sub>isol</sub>	Isolation Voltage	60Hz, Sinusoidal, Charged part to Base plate, AC 1min, RMS	2500	V

<sup>\*:</sup> Tc measurement point is just under the chip.

#### THERMAL RESISTANCE

Symbol	Parameter	Conditions		Unit		
		Conditions	Min.	Тур.	Max.	Unit
$R_{th(j-c)Q}$	Thermal Resistance	Inverter, Junction to case, IGBT, per 1 element (Note1)	-	-	0.12	
$R_{th(j-c)D}$		Inverter, Junction to case, FWD, per 1 element (Note1)	-	-	0.19	K/W
$R_{th(j-c)Q}$		Brake, Junction to case, IGBT, per 1 element (Note1)	-	-	0.21	
$R_{th(j-c)D}$		Brake, Junction to case, FWD, per 1 element (Note1)	-	-	0.34	
R <sub>th(c-s)</sub>	Contact Thermal Resistance	Case to heat sink, per 1 module,	_	- 8.4	_	K/kW
		Thermal grease applied (Note.1, 2, 5)				IVIKVV

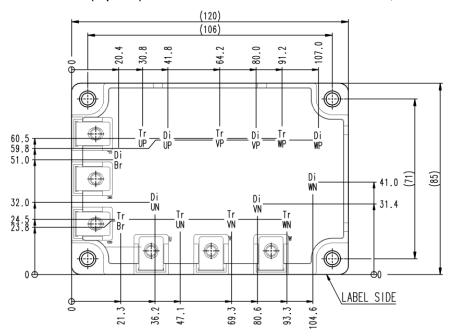
Note1. If you use this value,  $R_{\text{th(s-a)}}$  should be measured just under the chips.

Note2. Typical value is by thermally conductive grease of  $\lambda$ =0.9W/(m·K), D<sub>(C-S)</sub>=50  $\mu$ m.

#### **CHIP LOCATION (Top view)**

Publication date: December, 2020

Dimension in mm, torelance: ±1mm



Tr\*\* : IGBT Di\*\* : FWD

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## **ELECTRICAL CHARACTERISTICS** (Tvj= 25°C, unless otherwise noted)

### **INVERTER PART**

Come le el	Davassatas	Conditions			Limits			Llmia		
Symbol	Parameter				Min.	Тур.	Max.	Unit		
		V =15 V I =200 A	Tv:=05 °C	Terminal	-	-	2.05			
V	Collector-Emitter Saturation Voltage	V <sub>D</sub> =15 V, I <sub>C</sub> =300 A	Tvj=25 °C	Chip	-	1.25	-	V		
V <sub>CEsat</sub>	· ·	\/ =0\/ Dulood (Fig.1)	Tvj=125 °C	Terminal	-	-	2.3	V		
		V <sub>CIN</sub> =0 V, Pulsed, (Fig.1)	1 Vj - 125 C	Chip	-	1.33	-			
		V <sub>D</sub> =15 V, I <sub>E</sub> =300A,	Tvj=25 °C	Terminal	-	-	2.1	V		
V <sub>EC</sub>	V Callester Volters		1 Vj-25 C	Chip	-	1.40	1			
VEC	Emitter-Collector Voltage	V <sub>CIN</sub> = 15 V, pulsed, (Fig.2) Tvj=125 °C	Tvi=125 °C	Terminal	-	-	2.2			
			1 Vj=125 C	Chip	-	1.45	•			
ton		$V_D=15 \text{ V}, V_{CIN}=0 \text{ V} \longleftrightarrow 15 \text{ V},$ $V_{CC}=300 \text{ V}, I_C=300\text{A},$ $Tvj=125 \text{ °C},$		0.3	0.6	1.2				
t <sub>rr</sub>				-	0.2	0.65				
t <sub>c(on)</sub>	Switching Time				-	0.2	0.75	μs		
t <sub>off</sub>		Inductive Load			- 1.	1.1	2.3			
t <sub>c(off)</sub>		(Fig.3, 4)			-	0.16	0.4			
	Collector Emitter Cut off Current	V <sub>CE</sub> =V <sub>CES</sub> , V <sub>D</sub> =15 V,		Tvj=25 °C	-	-	1	m A		
I <sub>CES</sub>	Collector-Emitter Cut-off Current	V <sub>CIN</sub> =15 V (Fig.5)	\	<sub>CIN</sub> =15 V (Fig.5)	Tvj=	Tvj=125 °C	-	-	10	mA

#### **BRAKE PART**

Symbol	Parameter	Conditions		Limits			Unit	
Symbol	Farameter	Condition	Conditions		Min.	Тур.	Max.	Offic
		V <sub>D</sub> =15 V, I <sub>C</sub> =150A	Tvj=25 °C	Terminal	-	-	1.9	
	Collector Emitter Seturation Voltage	VD-13 V, 16-130A	1 Vj-25 C	Chip	-	1.25	-	V
$V_{CEsat}$	Collector-Emitter Saturation Voltage	V <sub>CIN</sub> =0 V, Pulsed, (Fig.1)	Tvj=125 °C	Terminal	-	-	2.1	-
				Chip	-	1.33	-	
	Diode Forward Voltage	I <sub>F</sub> =150A	Tvj=25 °C	Terminal	-	-	2.0	- ×
\/				Chip	-	1.40	-	
$V_{FM}$			T: 405 %	Terminal	-	-	2.1	
			Tvj=125 °C	Chip	-	1.45	-	
	Collector-Emitter Cut-off Current	V <sub>CE</sub> =V <sub>CES</sub> , V <sub>D</sub> =15 V, V <sub>CIN</sub> =15 V (Fig.5)		Tvj=25 °C	-	-	1	mA
I <sub>CES</sub>				Tvj=125°C	-	-	10	IIIA

HIGH POWER SWITCHING USE

INSULATED TYPE

# **ELECTRICAL CHARACTERISTICS** (Tvj = 25°C, unless otherwise noted)

#### **CONTROL PART**

Cymphal	Parameter	Conditions	Conditions		Limits		
Symbol	Parameter	Conditions			Тур.	Max.	Unit
		V <sub>D</sub> =15 V, V <sub>CIN</sub> =15 V	V <sub>P1</sub> -V <sub>PC</sub>	-	4	6	
	Circuit Current	V <sub>D</sub> -13 V, V <sub>CIN</sub> -13 V	V <sub>N1</sub> -V <sub>NC</sub>	-	16	24	m 1
I <sub>D</sub>	Circuit Current	$V_D$ =15 V, $V_{CIN}$ =0 V $\longleftrightarrow$ 15 V, $V_{CC}$ =400 V	V <sub>P1</sub> -V <sub>PC</sub>	-	36	44	mA
		I <sub>C</sub> =0A, Tvj=125 °C, f <sub>C</sub> ≤20kHz	V <sub>N1</sub> -V <sub>NC</sub>	-	129	151	
$V_{th(ON)}$	Input ON Threshold Voltage	Applied between:		1.2	1.5	1.8	V
$V_{th(OFF)}$	Input OFF Threshold Voltage	$U_{P}\text{-}V_{UPC},V_{P}\text{-}V_{VPC},W_{P}\text{-}V_{WPC},U_{N},V_{N},W_{N},$	Br-V <sub>NC</sub>	1.7	2.0	2.3	V
sc	Short Circuit Trip Level	-20≤Tvj≤125 °C, V <sub>D</sub> =15 V (Fig.3, 6)	Inverter	600	-	-	A
			Brake	300	-	-	
t <sub>d(SC)</sub>	Short Circuit Current Delay Time	V <sub>D</sub> =15 V, Tvj=125 °C (Fig.3, 6)	•	-	2.0	-	μs
ОТ	Over Temperature Burst still	Detect temperature of IGBT chip surface	Trip level	150	-	-	00
OT <sub>(hys)</sub>	Over Temperature Protection		Hysteresis	-	20	-	°C
UV <sub>t</sub>	Supply Circuit		Trip level	11.0	12.0	12.7	
UV <sub>r</sub>	Under-Voltage Protection	-	Reset level	-	12.5	-	V
I <sub>FO(H)</sub>	Facility Control of Community	V 45 V V 45 V (Note 0)		-	-	0.01	4
I <sub>FO(L)</sub>	Fault Output Current	V <sub>D</sub> =15 V, V <sub>FO</sub> =15 V (Note3)		-	10	15	mA
			ОТ	-	8.0	-	ms
t <sub>FO</sub>	Fault Output Pulse Width	V <sub>D</sub> =15 V (Note3)	UV	-	4.0	-	
			SC	-	2.0	-	

Note3. Fault output is given only when the internal SC, OT & UV protections schemes of either upper or lower arm device operate to protect it.

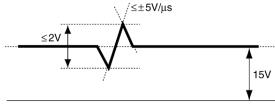
#### **MECHANICAL RATINGS AND CHARACTERISTICS**

Symbol	Parameter	Conditions		Limits		
				Тур.	Max.	Unit
Ms	Mounting Torque	Mounting part screw : M	2.5	3.0	3.5	Nama
$M_t$	Mounting Torque	Main terminal part screw : M	5 2.5	3.0	3.5	N•m
m	mass	-	-	425	-	g

#### **RECOMMENDED CONDITIONS FOR USE**

Symbol	Parameter	Conditions	Recommended value	Unit
V <sub>cc</sub>	Supply Voltage	Applied across P-N terminals	≤ 400	V
V <sub>D</sub>	Control Supply Voltage	Applied between : V <sub>UP1</sub> -V <sub>UPC</sub> , V <sub>VP1</sub> -V <sub>VPC</sub> , V <sub>WP1</sub> -V <sub>WPC</sub> , V <sub>N1</sub> -V <sub>NC</sub> (Note4)	15.0±1.5	V
V <sub>CIN(ON)</sub>	Input ON Voltage	Applied between :	≤ 0.8	
V <sub>CIN(OFF)</sub>	Input OFF Voltage	UP-VUPC, VP-VVPC, WP-VWPC, UN, VN, WN, Br-VNC	≥ 9.0	7 V
f <sub>PWM</sub>	PWM Input Frequency	Using Application Circuit of Fig. 8	≤ 20	kHz
t <sub>dead</sub>	Arm Shoot-through Blocking Time	For IPM's each input signals (Fig.7)	≥ 2.0	μs

Note4. With ripple satisfying the following conditions: dv/dt swing  $\leq \pm 5$   $V/\mu s$ , Variation  $\leq 2$  V peak to peak



GND

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Note5. Long term performance related to thermal conductive material such as thermal grease (including but not limited to aspects such as the increase of thermal resistance due to pumping out, etc.) should be verified under your specific application conditions. Each temperature condition (Tvj, Tc) must be maintained below the maximum rated temperature throughout consideration of the temperature rise even for long term usage.

HIGH POWER SWITCHING USE

#### **INSULATED TYPE**

#### PRECAUTIONS FOR TESTING

- 1. Before applying any control supply voltage (V<sub>D</sub>), the input terminals should be pulled up by resistors, etc. to their corresponding supply voltage and each input signal should be kept off state.
  - After this, the specified ON and OFF level setting for each input signal should be done.
- 2. When performing "SC" tests, the turn-off surge voltage spike at the corresponding protection operation should not be allowed to rise above V<sub>CES</sub> rating of the device.

(These test should not be done by using a curve tracer or its equivalent.)

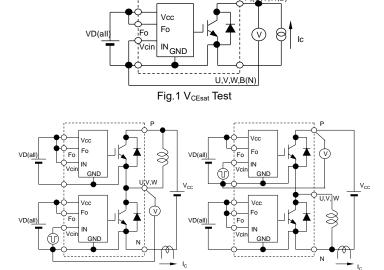
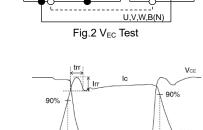


Fig.3 Switching time and SC test circuit



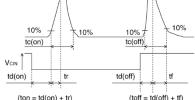


Fig.4 Switching time test waveform

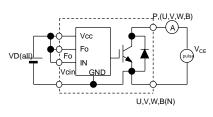


Fig.5 I<sub>CES</sub> Test

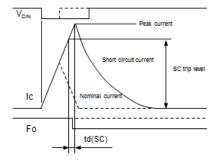
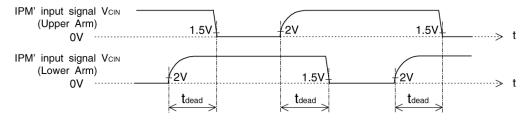


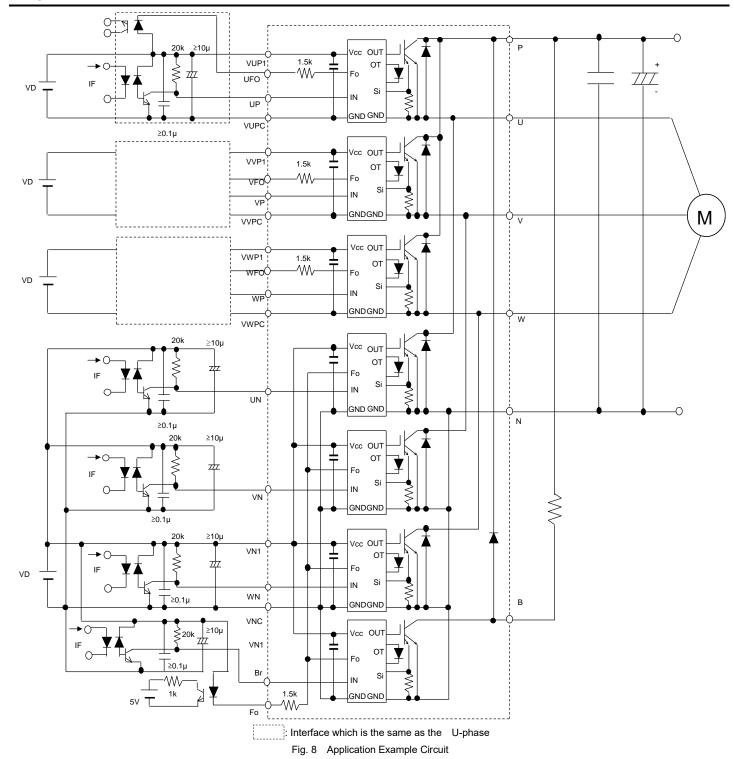
Fig.6 SC test waveform



1.5V: Input on threshold voltage Vth(on) typical value, 2V: Input off threshold voltage Vth(off) typical value

Fig. 7 Dead time measurement point example

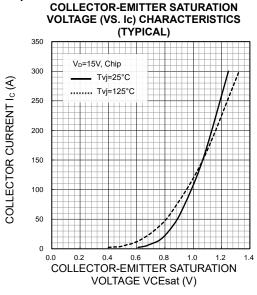
**INSULATED TYPE** 



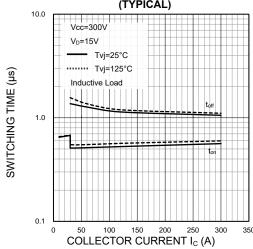
## NOTES FOR STABLE AND SAFE OPERATION;

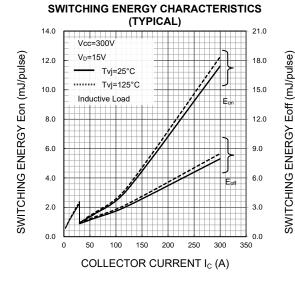
- Design the PCB pattern to minimize wiring length between opto-coupler and IPM's input terminal, and also to minimize the stray capacity between the input and output wirings of opto-coupler.
- · Connect low impedance capacitor between the Vcc and GND terminal of each fast switching opto-coupler.
- Fast switching opto-couplers: t<sub>PLH</sub>, t<sub>PHL</sub> ≤ 0.8µs, Use High CMR type.
- Slow switching opto-coupler: CTR > 100% (\*can be applied to Brake part input signal, in this case, resistor should be selected properly).
- Use 4 isolated control power supplies (V<sub>D</sub>). Also, care should be taken to minimize the instantaneous voltage charge of the power supply.
- Make inductance of DC bus line as small as possible, and minimize surge voltage using snubber capacitor between P and N terminal.

# PERFORMANCE CURVES Inverter part

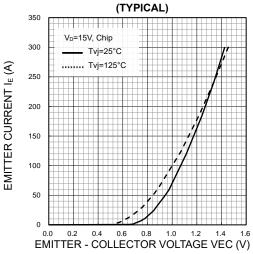


# O.0 0.2 0.4 0.6 0.8 1.0 COLLECTOR-EMITTER SATURA VOLTAGE VCEsat (V) SWITCHING TIME (ton, toff) CHARACTERISTICS (TYPICAL)

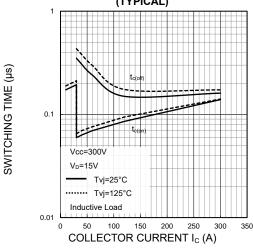




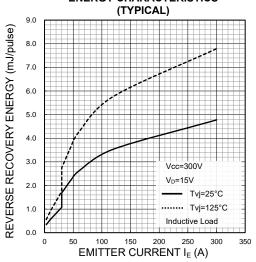
FREE WHEELING DIODE FORWARD
CHARACTERISTICS
(TYPICAL)



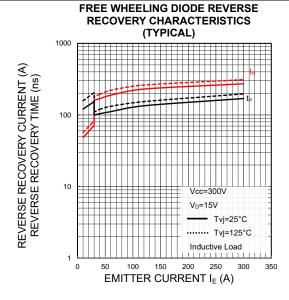
SWITCHING TIME  $(t_{c(on)}, t_{c(off)})$ CHARACTERISTICS (TYPICAL)

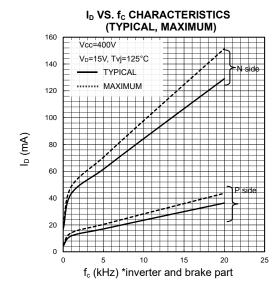


# FREE WHEELING DIODE REVERSE RECOVERY ENERGY CHARACTERISTICS

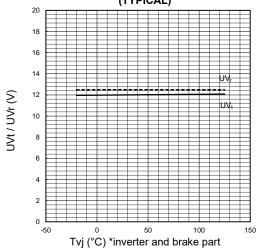


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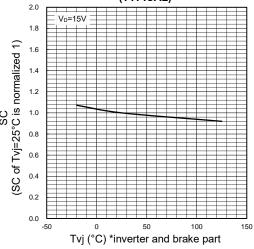




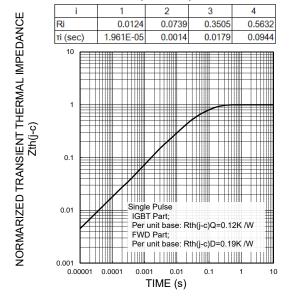
# UV TRIP LEVEL VS. Tvj CHARACTERISTICS (TYPICAL)



# SC TRIP LEVEL VS. TVJ CHARACTERISTICS (TYPICAL)



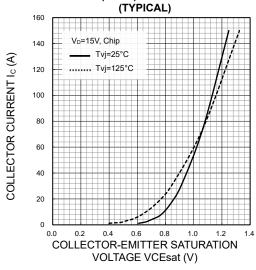
#### TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (TYPICAL)



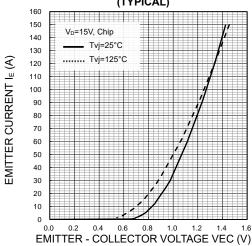
#### **INSULATED TYPE**

# PERFORMANCE CURVES Brake part

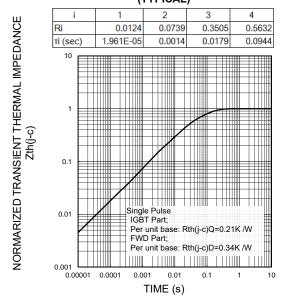
#### COLLECTOR-EMITTER SATURATION VOLTAGE (VS. Ic) CHARACTERISTICS (TYPICAL)



#### FREE WHEELING DIODE FORWARD CHARACTERISTICS (TYPICAL)



#### TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (TYPICAL)



#### Note:

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The characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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## **Important Notice**

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